

### SUBMINIATURE SOLID STATE LAMP

PRELIMINARY SPEC

Part Number: AM27SURCK03

Hyper Red

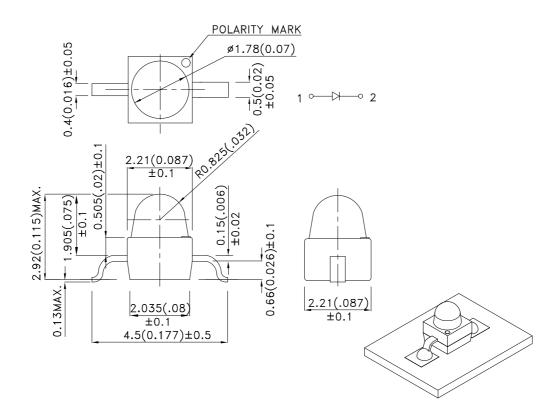
### **Features**

- SUBMINIATURE PACKAGE.
- GULL WING.
- LONG LIFE SOLID STATE RELIABILITY.
- LOW PACKAGE PROFILE.
- PACKAGE :1000PCS / REEL.
- MOISTURE SENSITIVITY LEVEL : LEVEL 3.
- RoHS COMPLIANT.

## **Description**

The Hyper Red source color devices are made with DH InGaAIP on GaAs substrate Light Emitting Diode.

## **Package Dimensions**



### Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is  $\pm 0.25(0.01")$  unless otherwise noted.
- 3. Lead spacing is measured where the leads emerge from the package.
- 4. Specifications are subject to change without notice.
- 5. The device has a single mounting surface. The device must be mounted according to the specifications.

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## **Selection Guide**

Part No.	lv (mcd) [2] Dice Lens Type @ 20mA			Viewing Angle [1]	
			Min.	Тур.	201/2
AM27SURCK03	Hyper Red (InGaAIP)	WATER CLEAR	480	1400	20°

- 1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value. 2. Luminous intensity/ luminous Flux: +/-15%.

## Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Hyper Red	650		nm	IF=20mA
λD [1]	Dominant Wavelength	Hyper Red	635		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Hyper Red	28		nm	IF=20mA
С	Capacitance	Hyper Red	35		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Hyper Red	1.95	2.5	V	IF=20mA
lr	Reverse Current	Hyper Red		10	uA	V <sub>R</sub> =5V

1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

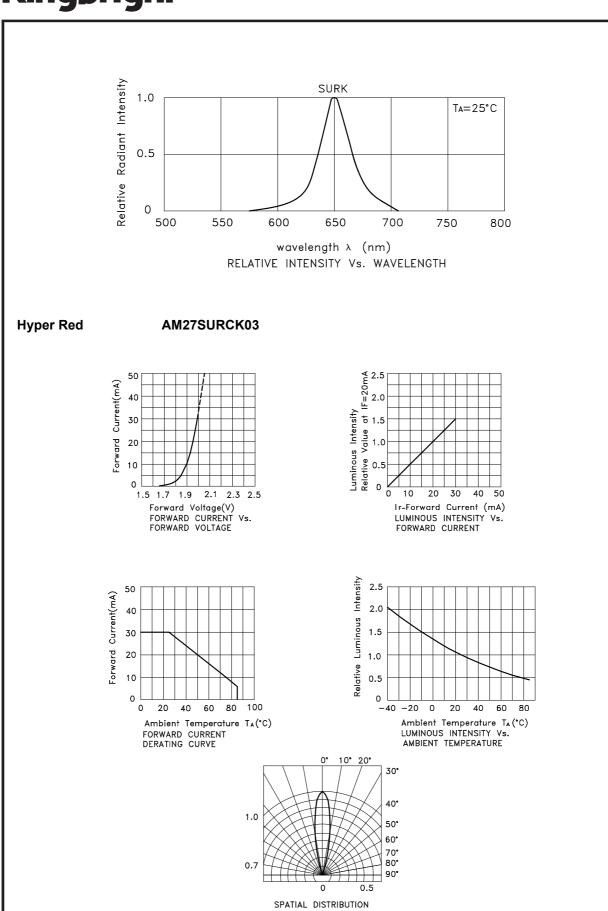
## Absolute Maximum Ratings at TA=25°C

Parameter	Hyper Red	Units	
Power dissipation	75	mW	
DC Forward Current	30	mA	
Peak Forward Current [1]	185	mA	
Reverse Voltage	5	V	
Operating Temperature	-40°C To +85°C		
Storage Temperature	-40°C To +85°C		

## Note:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.

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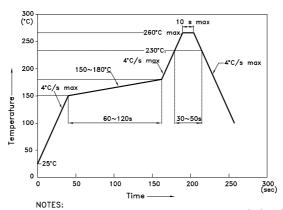


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## AM27SURCK03

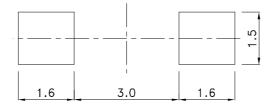
Reflow Soldering Profile For Lead-free SMT Process.



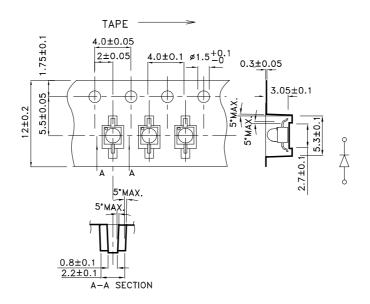
- NOTES:

  1.We recommend the reflow temperature 245°C(+/-5°C).The maximum soldering temperature should be limited to 260°C. 2.Don't cause stress to the epoxy resin while it is exposed to high temperature.
   3.Number of reflow process shall be 2 times or less.

**Recommended Soldering Pattern** (Units: mm; Tolerance: ± 0.1)



## **Tape Specifications** (Units: mm)

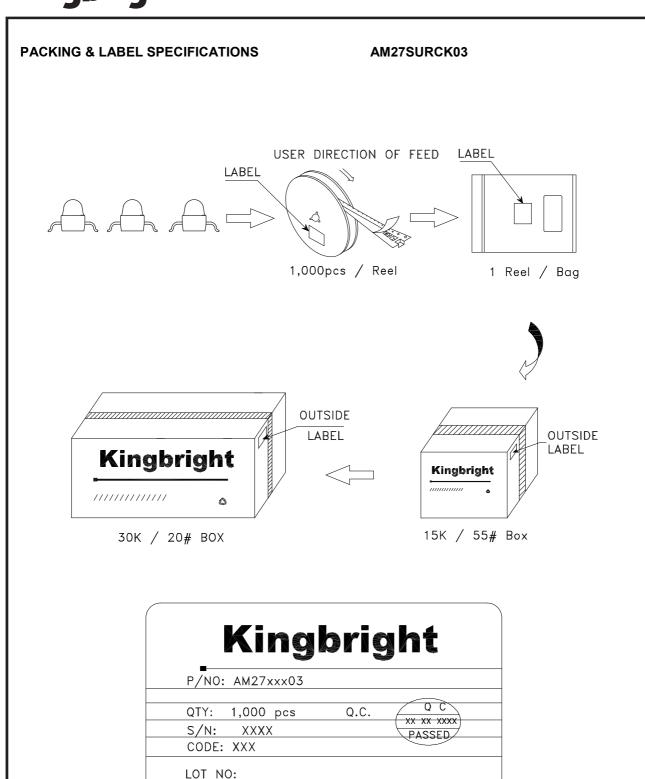


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RoHS Compliant

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